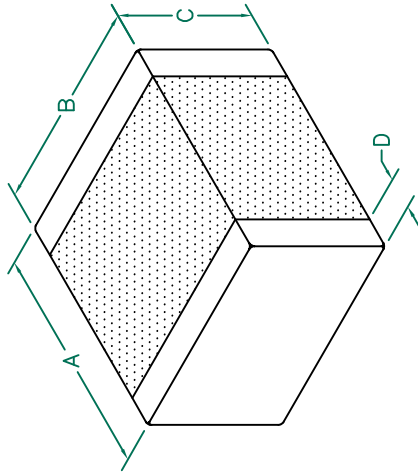


HI2220P601R-10

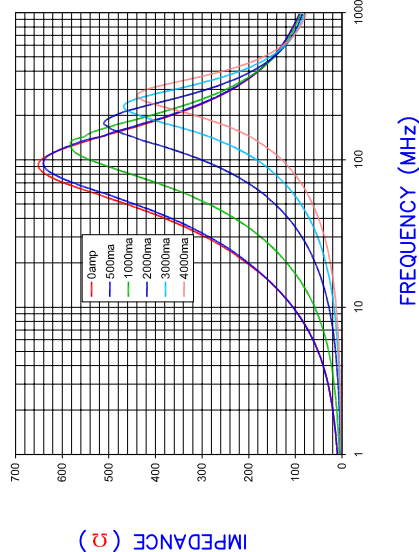
UNCONTROLLED
DOCUMENT

PHYSICAL DIMENSIONS:

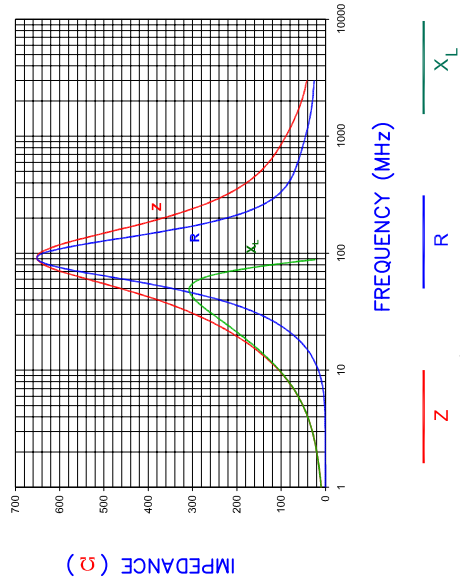
A	5.59 [.220]	± 0.51 [.020]
B	5.08 [.200]	± 0.25 [.010]
C	3.05 [.120]	± 0.25 [.010]
D	0.76 [.030]	± 0.25 [.010]



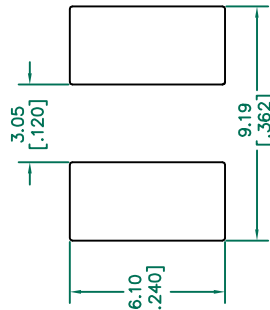
Z vs FREQUENCY
IMPEDANCE UNDER DC BIAS



|Z|, R, AND X vs. FREQUENCY

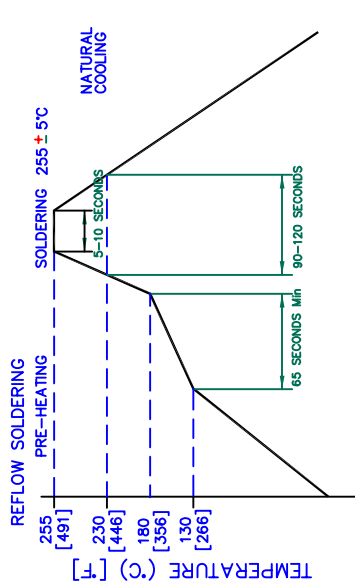


LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 (0.30) to this dimension.)

RECOMMENDED SOLDERING CONDITIONS



NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 13" REELS, 2,000 PCS/REEL.
2. U.S. PATENT 5,821,846 AND 6,107,907 SHOULD APPEAR ON THE LABEL OF EACH REEL OF PACKAGED PARTS.
3. TERMINATION FINISH IS 100% TIN.
4. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
5. OPERATING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

ELECTRICAL CHARACTERISTICS:

Z @ 100MHz (Ω)	DCR (Ω)	Rated Current
Nominal	600	
Minimum	450	
Maximum	750	4000 mA

RoHS
2002/95/EC

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PROJECT/PART NUMBER		REV	PART TYPE	DRAWN BY:
E		08/05/13	QU	BAC
D		01/24/08	JRK	
C		05/11/04	JRK	
B		03/19/03	JRK	
A		01/12/01	BAC	
DATE		DATE	INT	
DESCRIPTION		DATE	INT	
ADD OPERATING TEMPERATURE		08/05/13	QU	
UPDATE LAIRD LOGO AND REFLOW CURVE		08/05/13	QU	
UPDATE COMPANY LOGO ADD ROHS		01/24/08	JRK	
CHANGE C DIMENSION FROM .130		05/11/04	JRK	
ADD DC BIAS CURVE, CHG DCR RATING		03/19/03	JRK	
ORIGINAL DRAFT		01/12/01	BAC	
DATE		DATE	INT	
DESCRIPTION		DATE	INT	
DIMENSIONS ARE IN mm [INCHES]		DATE	INT	
Laird		DATE	INT	
2 of 2		DATE	INT	